

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

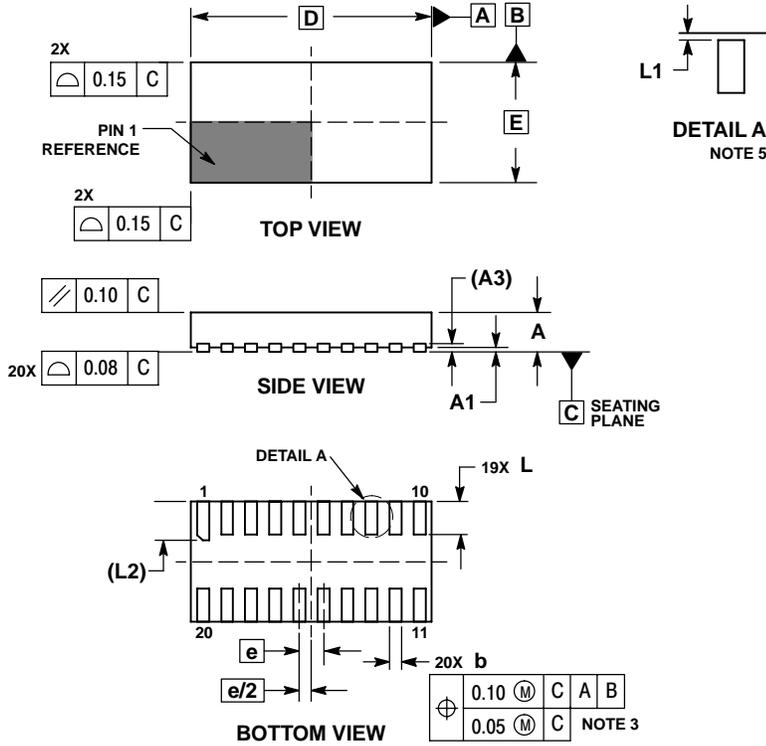
ON Semiconductor®



UDFN20 4x2, 0.4P  
CASE 517AK-01  
ISSUE O

DATE 14 NOV 2006

SCALE 4:1

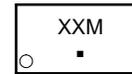


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
4. MOLD FLASH ALLOWED ON TERMINALS ALONG EDGE OF PACKAGE. FLASH MAY NOT EXCEED 0.03 ONTO BOTTOM SURFACE OF TERMINALS.
5. DETAIL A SHOWS OPTIONAL CONSTRUCTION FOR TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	4.00 BSC	
E	2.00 BSC	
e	0.40 BSC	
L	0.50	0.60
L1	0.00	0.03
L2	0.60	0.70

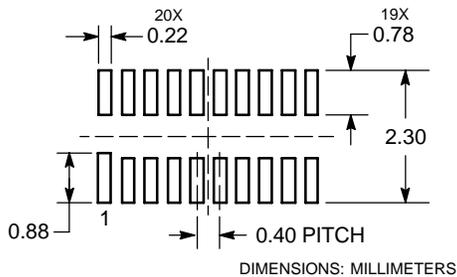
**GENERIC MARKING DIAGRAM\***



- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

**MOUNTING FOOTPRINT  
SOLDERMASK DEFINED**



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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	UDFN20 4 X 2, 0.4P	PAGE 1 OF 2

